

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5949419

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	SECURITY AGREEMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	MICROSS ADVANCED INTERCONNECT TECHNOLOGY LLC	02/05/2020
	SILICON TURNKEY SOLUTIONS, INC.	02/05/2020
RECEIVING PARTY DATA		
Name:	ALLY BANK, AS ASSIGNEE	
Street Address:	300 PARK AVENUE	
Internal Address:	4TH FLOOR	
City:	NEW YORK	
State/Country:	NEW YORK	
Postal Code:	10022	
PROPERTY NUMBERS Total: 33		
Property Type	Number	
Patent Number:	10418344	
Patent Number:	10209175	
Patent Number:	10125599	
Patent Number:	9881905	
Patent Number:	9576889	
Patent Number:	9437796	
Patent Number:	9257335	
Patent Number:	9022649	
Patent Number:	8975753	
Patent Number:	8766656	
Patent Number:	8486765	
Patent Number:	8404585	
Patent Number:	8361901	
Patent Number:	8222086	
Patent Number:	8198974	
Patent Number:	8129834	
Patent Number:	8035223	
Patent Number:	8008134	

Property Type	Number
Patent Number:	7999388
Patent Number:	7978029
Patent Number:	7944041
Patent Number:	7831874
Patent Number:	7829994
Patent Number:	7764498
Patent Number:	7709966
Patent Number:	7042306
Patent Number:	6752868
Patent Number:	6731492
Patent Number:	6456420
Patent Number:	6396620
Patent Number:	6377438
Patent Number:	6373682
Application Number:	16277287

CORRESPONDENCE DATA

Fax Number: (800)914-4240

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 8007130755

Email: james.murray@wolterskluwer.com

Correspondent Name: CT CORPORATION

Address Line 1: 4400 EASTON COMMONS WAY

Address Line 2: SUITE 125

Address Line 4: COLUMBUS, OHIO 43219

NAME OF SUBMITTER:	CORENDA R. LEWIS
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SIGNATURE:	/Corenda R. Lewis/
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DATE SIGNED:	02/06/2020
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Total Attachments: 6

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RECORDATION FORM COVER SHEET
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

MICROSS ADVANCED INTERCONNECT TECHNOLOGY LLC
SILICON TURNKEY SOLUTIONS, INC.

2. Name and address of receiving party(ies)

Name: ALLY BANK, as Assignee

Internal Address: _____

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) February 5, 2020

☐ Assignment

☐ Merger

☒ Security Agreement

☐ Change of Name

☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other _____

Street Address: 300 Park Avenue, 4th Floor

City: New York

State: New York

Country: USA Zip: 10022

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)
See Exhibit A attached

B. Patent No.(s)
See Exhibit A attached

Additional numbers attached? ☒ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Corenda R. Lewis

Internal Address: c/o Hahn & Hessen LLP

Street Address: 488 Madison Avenue

City: New York

State: New York Zip: 10022

Phone Number: 212-478-7200

Fax Number: _____

Email Address: clewis2@hahnhausen.com

6. Total number of applications and patents involved: 33

7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____

☐ Authorized to be charged by credit card

☐ Authorized to be charged to deposit account

☐ Enclosed

☐ None required (government interest not affecting title)

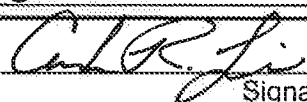
8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name _____

9. Signature:



Signature

February 5, 2020

Date

Corenda R. Lewis

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: _____

\$

NOTICE OF SECURITY INTEREST IN PATENTS

United States Department of Commerce
Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

Ladies and Gentlemen:

Pursuant to that certain Security Agreement, dated as of February 5, 2020 (as amended, restated, amended and restated, supplemented, extended, refinanced or otherwise modified from time to time, the "Security Agreement"), each of Micross Advanced Interconnect LLC, a Delaware limited liability company ("Micross") and Silicon Turnkey Solutions, Inc., a California corporation ("STS" and, together with Micross, collectively, the "Assignors" and each, an "Assignor") grants to Ally Bank, not in its individual capacity but solely as administrative agent for the Lenders under the Credit Agreement referenced in the Security Agreement, as Assignee (the "Assignee") a lien on and security interest in, to and under the Patents (as such term is defined in the Security Agreement) including the patents and patent applications listed on the annexed Exhibit A, together with any and all (i) applications and, registrations, renewals and proceeds (including accounts receivable and royalties) thereof, (ii) rights and privileges arising under applicable legal requirements with respect to the use of any of the foregoing, (iii) inventions and improvements described and claimed therein, (iv) reissues, substitutes, reexaminations, divisionals, renewals, extensions, continuations and continuations-in-part thereof and amendments thereto, (v) proceeds, income, fees, royalties, damages and payments now or hereafter due and/or payable thereunder and with respect thereto including damages, claims and payments for past, present or future infringements or other violations thereof, (vi) rights to sue for past, present or future infringements or other violations thereof, and (vii) rights corresponding thereto throughout the world. The Assignee's security interest in the Patents can only be terminated in accordance with the terms of the Security Agreement.

Dated: February 5, 2020

[Signature Pages Follow]

Very truly yours,

**MICROSS ADVANCED INTERCONNECT
TECHNOLOGY LLC**

By: Kent D. Rosenthal
Name: Kent Rosenthal
Title: Chief Financial Officer

SILICON TURNKEY SOLUTIONS, INC.

By: Kent D. Rosenthal
Name: Kent Rosenthal
Title: Chief Financial Officer

ACKNOWLEDGED BY:

ALLY BANK,
as Assignee

By: W. Wakefield Smith
Name: W. Wakefield Smith
Title: Authorized Signatory

[Signature Page to Memorandum of Security Interest in Patents]

PATENT
REEL: 051836 FRAME: 0702

EXHIBIT A

Registered Patents

<u>ASSIGNOR</u>	<u>TITLE</u>	<u>PATENT NUMBER</u>	<u>REGISTRATION DATE</u>
Micross Advanced Interconnect Technology LLC	Electronic Packages with Three-Dimensional Conductive Planes, and Methods for Fabrication	10,418,344	30-Jan-18
Micross Advanced Interconnect Technology LLC	Detection of Corrosion Using Dispersed Embedded Sensors	10,209,175	19-Feb-19
Micross Advanced Interconnect Technology LLC	Location of sensors in Well Formations	10,125,599	13-Nov-18
Micross Advanced Interconnect Technology LLC	Electronic Packages with Three-Dimensional Conductive Planes, and Methods for Fabrication	9,881,905	30-Jan-18
Micross Advanced Interconnect Technology LLC	Three- Dimensional Electronic Packages Utilizing Unpatterned Adhesive Layer	9,576,889	21-Feb-17
Micross Advanced Interconnect Technology LLC	Rare Earth-Doped Materials With Enhanced Thermoelectric Figure of Merit	9,437,796	6-Sep-16
Micross Advanced Interconnect Technology LLC	Electronic Devices Utilizing Contact Pads with Protrusions and Methods for Fabrication	9,257,335	9-Feb-16
Micross Advanced Interconnect Technology LLC	Fluorescence Based Thermometry	9,022,649	5-May-15
Micross Advanced Interconnect Technology LLC	Three Dimensional Interconnect Structure and Method Thereof	8,975,753	10-Mar-15
Silicon Turnkey Solutions, Inc.	Systems and Methods for Thermal Control	8,766,656	1-Jul-14
Micross Advanced Interconnect Technology LLC	Structure and Process for Electrical Interconnect & Thermal Management	8,486,765	16-Jul-13
Micross Advanced Interconnect Technology LLC	Preventing Breakage of Long Metal Signal Conductors on Semiconductor Substrates	8,404,585	26-Mar-13
Micross Advanced Interconnect Technology LLC	Die Bonding Utilizing a Patterned Adhesion Layer	8,361,901	29-Jan-13
Micross Advanced Interconnect Technology LLC	Integrated Semiconductor Substrate Structure Using Incompatible Processes	8,222,086	17-Jul-12
Micross Advanced Interconnect Technology LLC	Flexible Electrostatic Actuator	8,198,974	12-Jun-12
Micross Advanced Interconnect Technology LLC	Integral Metal Structure With Conductive Post Portions	8,129,834	6-Mar-12
Micross Advanced Interconnect Technology LLC	Structure and Process for Electrical Interconnect and Thermal Management	8,035,223	11-Oct-11

Micross Advanced Interconnect Technology LLC	Large Substrate Structural Vias	8,008,134	30-Aug-11
Micross Advanced Interconnect Technology LLC	Preventing Breakage of Long Metal Signal Conductors on Semiconductor Substrates	7,999,388	16-Aug-11
Micross Advanced Interconnect Technology LLC	Multiple-Layer Signal Conductor	7,978,029	12-Jul-11
Micross Advanced Interconnect Technology LLC	Integrated Semiconductor Substrate Structure Using Incompatible Processes	7,944,041	17-May-11
Micross Advanced Interconnect Technology LLC	Local Defect Memories on Semiconductor Substrates In a Stack Computer	7,831,874	9-Nov-10
Micross Advanced Interconnect Technology LLC	Semiconductor Substrate Elastomeric Stack	7,829,994	9-Nov-10
Micross Advanced Interconnect Technology LLC	Comb-Shaped Power Bus Bar Assembly Structure Having Integrated Capacitors	7,764,498	27-Jul-10
Micross Advanced Interconnect Technology LLC	Large Substrate Structural Vias	7,709,966	4-May-10
Micross Advanced Interconnect Technology LLC	Three Dimensional Multi-Mode and Optical Coupling Devices	7,042,306	9-May-06
Micross Advanced Interconnect Technology LLC	Layer-by-Layer Assembly of Photonic Crystals	6,752,868	22-Jun-04
Micross Advanced Interconnect Technology LLC	Overdrive Structures for Flexible Electrostatic Switch	6,731,492	4-May-04
Micross Advanced Interconnect Technology LLC	Microelectromechanical Elevating Structures	6,456,420	24-Sep-02
Micross Advanced Interconnect Technology LLC	Electrostatically Actuated Electromagnetic Radiation Shutter	6,396,620	28-May-02
Micross Advanced Interconnect Technology LLC	Hybrid Microelectromechanical System Tunable Capacitor and Associated Fabrication Methods	6,377,438	23-Apr-02
Micross Advanced Interconnect Technology LLC	Electrostatically Controlled Variable Capacitor	6,373,682	16-Apr-02

Patent Applications

ASSIGNOR	TITLE	APPLICATION NUMBER	FILING DATE
Micross Advanced Interconnect Technology LLC	Detection of Corrosion Using Dispersed Embedded Sensors	16/277,287	15-Feb-19